



Docket No.: 50232-074

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : Customer Number: 20277
Kazushi SANO, et al. : Confirmation Number: 7133
Serial No.: 10/633,556 : Group Art Unit: 1751
Filed: August 05, 2003 : Examiner: To be Assigned
For: COPPER PARTICLE CLUSTERS AND POWDER CONTAINING THE SAME
SUITABLE AS CONDUCTIVE FILLER OF CONDUCTIVE PASTE

REQUEST FOR CORRECTED FILING RECEIPT

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Attached is a copy of the Filing Receipt received from the U.S. Patent and Trademark Office in the above-referenced application. It is noted that the Foreign Priority information is incorrect. Attached is a copy of the Declaration and Power of Attorney Document, which evidences that the Foreign Priority information should read only: **JAPAN 11-362304 12/21/1999**. It is requested that a corrected filing receipt be issued.

Respectfully submitted,

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Date: January 7, 2004



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APPL NO.	FILING OR 371 (c) DATE	ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/633,556	08/05/2003	1751	750	50232-074	6	11	3

20277
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WASHINGTON, DC 20005-3096

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NOV - 5 2003

MW&E

CONFIRMATION NO. 7133

FILING RECEIPT



OC000000011158785

Date Mailed: 11/03/2003

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Kazushi Sano, Okayama-shi, JAPAN;
Yoshihiro Okada, Okayama-shi, JAPAN;
Hiromasa Miyoshi, Okayama-shi, JAPAN;
Yoshiomi Takada, Tokyo, JAPAN;

Assignment For Published Patent Application

DOWA MINING CO., LTD., Tokyo, JAPAN;

Domestic Priority data as claimed by applicant

This application is a DIV of 09/741,024 12/21/2000 PAT 6,620,344

Foreign Applications

~~JAPAN 11-150281 05/28/1999~~
JAPAN 11-362304 12/21/1999

If Required, Foreign Filing License Granted: 10/31/2003

Projected Publication Date: 02/12/2004

Non-Publication Request: No

Early Publication Request: No

Title

Copper particle clusters and powder containing the same suitable as conductive filler of conductive paste

Preliminary Class

252



**LICENSE FOR FOREIGN FILING UNDER
Title 35, United States Code, Section 184
Title 37, Code of Federal Regulations, 5.11 & 5.15**

GRANTED

The applicant has been granted a license under 35 U.S.C. 184, if the phrase "IF REQUIRED, FOREIGN FILING LICENSE GRANTED" followed by a date appears on this form. Such licenses are issued in all applications where the conditions for issuance of a license have been met, regardless of whether or not a license may be required as set forth in 37 CFR 5.15. The scope and limitations of this license are set forth in 37 CFR 5.15(a) unless an earlier license has been issued under 37 CFR 5.15(b). The license is subject to revocation upon written notification. The date indicated is the effective date of the license, unless an earlier license of similar scope has been granted under 37 CFR 5.13 or 5.14.

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NOT GRANTED

No license under 35 U.S.C. 184 has been granted at this time, if the phrase "IF REQUIRED, FOREIGN FILING LICENSE GRANTED" DOES NOT appear on this form. Applicant may still petition for a license under 37 CFR 5.12, if a license is desired before the expiration of 6 months from the filing date of the application. If 6 months has lapsed from the filing date of this application and the licensee has not received any indication of a secrecy order under 35 U.S.C. 181, the licensee may foreign file the application pursuant to 37 CFR 5.15(b).

Docket No.: _____

DECLARATION AND POWER OF ATTORNEY



As a below named inventor, I hereby declare that:

My residence, post office and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter claimed and for which a patent is sought on the invention entitled _____

Copper Particle Clusters and Powder Containing the Same

Suitable as Conductive Filler of Conductive Paste

the specification of which

☐ is attached hereto ☐ was filed on _____ as Application Serial No. _____

and was amended on _____ (if applicable)

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is known to me to be material to patentability in accordance with Title 37, Code of Federal Regulations, Section 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, Section 119(a)-(d) or Section 365(b) of any foreign application(s) for patent or inventor's certificate, or Section 365(a) of any PCT international application which designated at least one country other than the United States, listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s):

Priority Claimed

Number Country Day/Month/Year filed

Yes No

11-150281 Japan 28th May 1999

x

11-362304 Japan 21st December 1999

x

I hereby claim the benefit under 35 USC §119(e) of any United States provisional application(s) listed below.

Prior Provisional Application(s):

Application Number Filing Date

I hereby claim the benefit under Title 35, United States Code, Section 120 of any United States application(s), or Section 365(c) of any PCT international application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT international application in the manner provided by the first paragraph of Title 35, United States Code, Section 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, Section 1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

Prior U. S. Application(s):

Serial No. Filing Date

Status: Patented, Pending, Abandoned

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made

are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

I hereby appoint the following attorney(s) and/or agent(s): Stanislaus Aksman, Reg. No. 28,562; Edward A. Becker, Reg. No. 37,777; Stephen A. Becker, Reg. No. 26,527; William H. Beha, Reg. No. 38,038; John G. Bisbikis, Reg. No. 37,095; Kenneth L. Cage, Reg. No. 26,151; Stephen C. Carlson, Reg. No. 39,929; Paul Devinsky, Reg. No. 28,553; Laura A. Donnelly, Reg. No. 38,435; Margaret M. Duncan, Reg. No. 30,879; Brian E. Ferguson, Reg. No. 36,801; Michael F. Fogarty, Reg. No. 36,139; Wilhelm F. Gadiano, Reg. No. 37,136; Keith E. George, Reg. No. 34,111; John A. Hankins, Reg. No. 32,029; Thomas A. Jolly, Reg. No. 39,241; Eric J. Kraus, Reg. No. 36,190; Edward E. Kubasiewicz, Reg. No. 30,020; Robert E. LeBlanc, Reg. No. 17,219; Jack Q. Lever, Reg. No. 28,149; Raphael V. Lupo, Reg. No. 28,363; Christine F. Martin, Reg. No. 39,762; Michael E. McCabe, Jr., Reg. No. 37,182; James H. Meadows, Reg. No. 33,965; Michael A. Messina, Reg. No. 33,424; Joseph H. Paquin, Jr., Reg. No. 31,647; Craig L. Plastrik, Reg. No. 41,254; Robert L. Price, Reg. No. 22,685; Paul A. Roberts, Reg. No. 40,289; Gene Z. Robinson, Reg. No. 33,351; Joy Ann G. Serauskas, Reg. No. 27,952; Michele M. Schafer, Reg. No. 34,717; David J. Serbin, Reg. No. 30,589; Glenn Snyder, Reg. No. 41,428; Arthur J. Steiner, Reg. No. 26,106; David L. Stewart, Reg. No. 37,578; Leonid D. Thenor, Reg. No. 39,397; Keith J. Townsend, Reg. No. 40,358; Leon R. Turkevich, Reg. No. 34,035; Christopher D. Ward, Reg. No. 41,367; Damian G. Wasserbauer, Reg. No. 34,749; Aaron Weissstuch, Reg. No. P41,557; Edward J. Wise, Reg. No. 34,523; Alexander V. Yampolsky, Reg. No. 36,324; and Robert W. Zelnick, Reg. No. 36,976 all of

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with full power of substitution and revocation, to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith, and all future correspondence should be addressed to them.

Full name of sole or first inventor: Kazushi SANO

Inventor's signature: *Kazushi Sano*

Date: November 9, 2000

Residence: 14-1-101, Chikkousakae-machi, Okayama-shi, Okayama 702-8053 Japan

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Inventor's signature: *Yoshihiro Okada*

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Inventor's signature: *Hiromasa Miyoshi*

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Full name of fourth joint inventor: Yoshiomi TAKADA

Inventor's signature:

Yoshiomi Takada

Date: November 10, 200

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Citizenship: Japan

Post Office Address: 388-2-203, Suwa-machi, Hachioji-shi, Tokyo 193-0812 Japan

Full name of fifth joint inventor:

Inventor's signature:

Date:

Residence:

Citizenship:

Post Office Address:

Full name of sixth joint inventor:

Inventor's signature:

Date:

Residence:

Citizenship:

Post Office Address:

Full name of seventh joint inventor:

Inventor's signature:

Date:

Residence:

Citizenship:

Post Office Address:

Full name of eighth joint inventor:

Inventor's signature:

Date:

Residence:

Citizenship:

Post Office Address:

Full name of ninth joint inventor:

Inventor's signature:

Date:

Residence:

Citizenship:

Post Office Address:

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

(1) Kazushi SANO
(2) Yoshihiro OKADA
(3) Hiromasa MIYOSHI

(4) Yoshiomi TAKADA
(5) _____
(6) _____

who have made a certain new and useful invention, hereby sell, assign and transfer unto

DOWA MINING CO., LTD.
8-2, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-8282 JAPAN

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

Copper Particle Clusters and Powder Containing the Same
Suitable as Conductive Filler of Conductive Paste

(a) for which an application for United States Letters Patent was filed on _____, and identified by United States Serial No. _____; or

(b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the dates indicated aside our signatures:

INVENTORS

DATE SIGNED

1) Kazushi Sano
Name: Kazushi SANO
2) Yoshihiro Okada
Name: Yoshihiro OKADA
3) Hiromasa Miyoshi
Name: Hiromasa MIYOSHI
4) Yoshiomi Takada
Name: Yoshiomi TAKADA
5) _____
Name: _____
6) _____
Name: _____

November 9, 2000

November 9, 2000

November 9, 2000

November 10, 2000

